



RS3700-Q1 Automotive Single-Channel Linear LED Driver

1 FEATURES

- RS3700-Q1 AEC-Q100 Qualification is Ongoing
- Functional Safety Capable
 - Documentation Available to Aid Functional
 Safety System Design
- Single-Channel Constant-Current LED Driver with PWM Dimming
- Wide Input-Voltage Range: 4.5 V-40 V
- Constant Output Current, Adjustable by Sense Resistor
- Precision Current Regulation, Tolerance ±4.6%
- Maximum Current: 500 mA
- Heat Sharing with External Resistor (Only for RS3700B-Q1)
- Low Dropout Voltage (Current-Sense Voltage Drop Included)
 - Typical Dropout: 180 mV at 100 mA
- Diagnostics and Protection
 - LED Open-Circuit and Short-Circuit Detection with Auto-Recovery
 - Diagnostic-Enable with Adjustable Threshold for Low-Dropout Operation
 - Fault Bus up to 15 Devices, Configurable as Either One-Fails-All-Fail or Only-Failed-Channel Off
 - Low Quiescent Current and Fault-Mode Current (<450 μA per Device)
- Operating Junction Temperature Range: -40°C to 150°C

2 APPLICATIONS

- Automotive Convenience Lighting: Dome Light, Door Handles, Reading Lamp, and Miscellaneous Lamps
- Automotive Rear Lamp, Center High-Mounted Stop Lamp, Side Markers, Blind-Spot Detection Indicator, Charging Inlet Indicator
- General-Purpose LED Driver Applications

3 DESCRIPTIONS

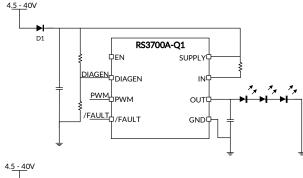
With LEDs being widely used in automotive applications, simple LED drivers are more and more popular. Compared to discrete solutions, a low-cost monolithic solution lowers system-level component counts and significantly improves current accuracy and reliability.

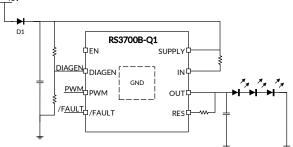
The RS3700-Q1 device is a simple single-channel high-side LED driver operating from an automotive car battery. It is a simple and elegant solution, with LED diagnostics, to deliver constant current for a single LED string. Its one-fails-all-fail feature is able to work together with other LED drivers to address different requirements.

Device Information (1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
RS3700-Q1	EMSOP8	3.00mm×3.00mm

 For all available packages, see the orderable addendum at the end of the data sheet.





Typical Application Diagram



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4 REVISION HISTORY

Note: Page numbers for previous revisions may different from page numbers in the current version.

Version	Change Date	Change Item
A.0	2025/04/22	Preliminary version completed



5 PACKAGE/ORDERING INFORMATION (1)

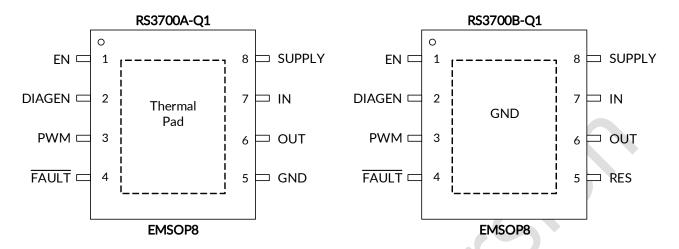
PRODUCT	ORDERING NUMBER	TEMPERATURE RANGE	PACKAGE LEAD	Lead finish/Ball material ⁽²⁾	MSL Peak Temp ⁽³⁾	PACKAGE MARKING	PACKAGE OPTION
RS3700-	RS3700AXEM-Q1	-40°C ~+125°C	EMSOP8	SN	TBD	RS3700A	Tape and Reel, 4000
Q1	RS3700BXEM-Q1	-40°C ~+125°C	EMSOP8	SN	TBD	RS3700B	Tape and Reel, 4000

NOTE:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) Lead finish/Ball material. Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (3) RUNIC classify the MSL level with using the common preconditioning setting in our assembly factory conforming to the JEDEC industrial standard J-STD-20F. Please align with RUNIC if your end application is quite critical to the preconditioning setting or if you have special requirement.
- (4) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.



6 PIN CONFIGURATIONS



PIN DESCRIPTION

PIN		I/O ⁽¹⁾	FUNCTION	
NAME	NO.	1/01-7	FUNCTION	
EN	1	I	Device enable pin	
DIAGEN	2	I	Enable pin for LED open-circuit detection to avoid false open diagnostics during low-dropout operation.	
PWM	3	I	PWM input for OUT and RES current output ON/OFF control.	
FAULT	4	I/O	Fault output, support one-fails-all-fail fault bus.	
GND	-	-	RS3700A-Q1: Ground.	
RES 5		-	RS3700B-Q1: Current output with thermal balancing shunt resistor.	
OUT	OUT 6		Current output for channel. A 10nF capacitor is recommended between the pin to GND.	
IN	7	I	Current input for channel.	
SUPPLY	8	1	Device power supply.	
Thermal pad	Thermal	-	RS3700A-Q1: Suggest to connect to GND.	
GND	Pad	-	RS3700B-Q1: Ground.	

⁽¹⁾ I=input, O=output.



7 SPECIFICATIONS

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

i G			MIN	MAX	UNIT
Supply	SUPPLY		-0.3	45	V
High-voltage input	DIAGEN, IN, EN, PWM		-0.3	V _{SUPPLY} +0.3	V
High-voltage output	OUT, RES		-0.3	V _{SUPPLY} +0.3	V
Fault bus	FAULT	FAULT		V _{SUPPLY} +0.3	٧
Αιθ	Package thermal impedance (2)	EMSOP8		60	°C/W
T _J	Operating junction temperature (3)		-40	150	ů
T _{stg}	Storage temperature		-40	150	°C

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT
		Human-Body Model (HBM), per AEC Q100-002 (1)	±4000	V
V(ESD)	Electrostatic discharge	Charged-Device Model (CDM), per AEC Q100-011	±1000	V
		Latch-Up (LU), per AEC Q100-004	TBD	mA

⁽¹⁾ AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
SUPPLY	Device supply voltage	4.5	40	V
IN	Sense voltage	Vsupply-Vcs_reg	V_{SUPPLY}	V
EN	Device EN pin	0	V_{SUPPLY}	V
PWM	PWM inputs	0	V_{SUPPLY}	V
DIAGEN	Diagnostics enable pin	0	V_{SUPPLY}	V
OUT, RES	Driver output	0	V_{SUPPLY}	V
FAULT	Fault bus	0	V_{SUPPLY}	V
Operating ambient temperature, T _A		-40	125	°C

⁽²⁾ The package thermal impedance is calculated in accordance with JESD-51.

⁽³⁾ The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A) / R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.



7.4 Electrical Characteristics

 $V_{SUPPLY}=5V$ to 40V, $V_{EN}=5V$, $T_{J}=-40^{\circ}C$ to $+150^{\circ}C$ unless otherwise noted.

	PARAMETER	TEST CONDITIONS	MIN ⁽¹⁾	TYP ⁽²⁾	MAX ⁽¹⁾	UNIT
BIAS						
VPOR_rising	Supply voltage POR rising threshold			3.67		V
VPOR_falling	Supply voltage POR falling threshold			3.53		٧
I _{SD}	Device shutdown current	V _{EN} = 0V, V _S =12V		5		μΑ
Quiescent	Device standby ground current	PWM=HIGH		0.45		mA
I _{Fault}	Device supply current in fault mode	PWM=HIGH, FAULT externally pulled LOW		0.2		mA
LOGIC INPU	rs (EN, DIAGEN, PWM)					
V _{IL_EN}	Input logic-low voltage, EN				0.7	V
V _{IH_EN}	Input logic-high voltage, EN		2			V
I _{EN_pulldown}	EN pulldown current	V _{EN} =12V		3.3		μΑ
VIL_DIAGEN	Input logic-low voltage, DIAGEN			1.1		V
V _{IH_DIAGEN}	Input logic-high voltage, DIAGEN			1.2		V
V _{IL_PWM}	Input logic-low voltage, PWM		,	1.1		V
V _{IH_PWM}	Input logic-high voltage, PWM			1.2		٧
CONSTANT-	CURRENT DRIVER			•		
louт	Device output-current	Duty of PWM=100%	4		500	mA
		T _A =25°C, V _{SUPPLY} =4.5V to 18V		98		mV
V_{CS_REG}	Sense-resistor regulation voltage	T _A =-40°C to +125°C, V _{SUPPLY} =4.5V to 18V		98		mV
R _{CS_REG}	Sense-resistor range				25	Ω
V _{DROPOUT}	Voltage dropout from IN to OUT, RES open Voltage dropout from IN to RES, OUT	Current setting of 100mA		180		mV
	open (Only for RS3700B-Q1)	>		240		
I _{RES}	Ratio of RES current to total current	IRES/IOUT_Tot, VIN-VRES>1V	95			%
DIAGNOSTIC	cs			•		
$V_{OPEN_th_rising}$	LED open rising threshold, V _{IN} - V _{OUT}			100		mV
$V_{OPEN_th_falling}$	LED open falling threshold, V_{IN} – V_{OUT}			300		mV
$V_{\text{SG_th_rising}}$	Channel output short-to-ground rising threshold			1.2		V
$V_{\text{SG_th_falling}}$	Channel output short-to-ground falling threshold			0.9		V
IRETRY	Channel output VouT short-to-ground retry current			1		mA

⁽¹⁾ Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

⁽²⁾ Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.



Electrical Characteristics (continued)

V_{SUPPLY}=5V to 40V, V_{EN}=5V, T_J=-40°C to +150°C unless otherwise noted.

	PARAMETER	TEST CONDITIONS	MIN ⁽¹⁾	TYP ⁽²⁾	MAX ⁽¹⁾	UNIT
FAULT						
VIL_FAULT	Logic input low threshold				0.7	V
VIH_FAULT	Logic input high threshold		2			V
Vol_fault	Logic output low threshold	With 500µA external pullup			0.4	V
Voh_fault	Logic output high threshold	With 1µA external pulldown, V _{SUPPLY} =12V	4			٧
tFAULT_rising	Fault detection rising edge deglitch time			10		μs
tFAULT_falling	Fault detection falling edge deglitch time			20		μs
IFAULT_pulldown	FAULT internal pulldown current	V _{FAULT} =0.4V		3		mA
IFAULT_pullup	FAULT internal pullup current			10		μΑ
THERMAL PR	OTECTION					
T _{TSD}	Thermal shutdown junction temperature threshold	0		170		°C
T _{TSD_HYS}	Thermal shutdown junction temperature hysteresis	16		15		°C

⁽¹⁾ Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

⁽²⁾ Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.



7.5 Timing Requirements

	PARAMETER	TEST CONDITIONS	MIN ⁽¹⁾	TYP ⁽²⁾	MAX ⁽¹⁾	UNIT
tPWM_delay_rising	PWM rising edge delay(V _{IH_PWM}) to 10% output	V _{SUPPLY} =12V, V _{OUT} =6V, I _{SET} =100mA		5		μs
tCurrent_rising	Output current rising from 10% to 90%	V _{SUPPLY} =12V, V _{OUT} =6V, I _{SET} =100mA		3		μs
tpwm_delay_falling	PWM falling edge delay(V _{IL_PWM}) to 90% output	V _{SUPPLY} =12V, V _{OUT} =6V, I _{SET} =100mA		5		μs
t _{Current_falling}	Output current rising from 90% to 10%	V _{SUPPLY} =12V, V _{OUT} =6V, I _{SET} =100mA		3		μs
tstartup	EN rising edge to 10% output current	V _{SUPPLY} =12V, V _{OUT} =6V, I _{SET} =100mA		85		μs
topen_deg	LED-open fault deglitch time			125		μs
tsG_deg	Output short-to-ground detection deglitch time			125		μs
t _{Recover_deg}	Open and Short fault recovery deglitch time		, C	125		μs
tFAULT_recovery	Fault recovery delay time			16		μs
t _{TSD_deg}	Thermal over temperature deglitch time	0		60		μs

⁽¹⁾ Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

⁽²⁾ Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.



7.6 Typical Characteristics

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

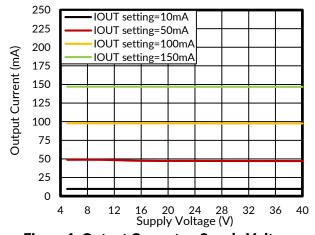


Figure 1. Output Current vs Supply Voltage

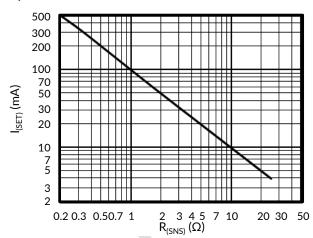


Figure 2. Output Current vs Current-Sense Resistor

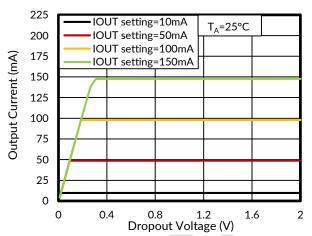


Figure 3. Output Current vs Dropout Voltage

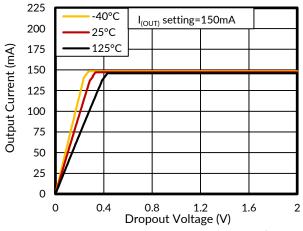


Figure 4. Output Current vs Dropout Voltage

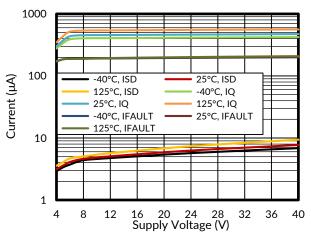


Figure 5. Shutdown, Quiescent, and Fault Current vs Supply Voltage

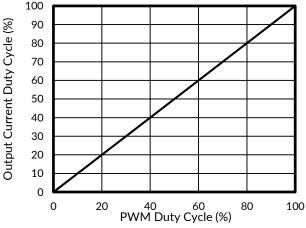
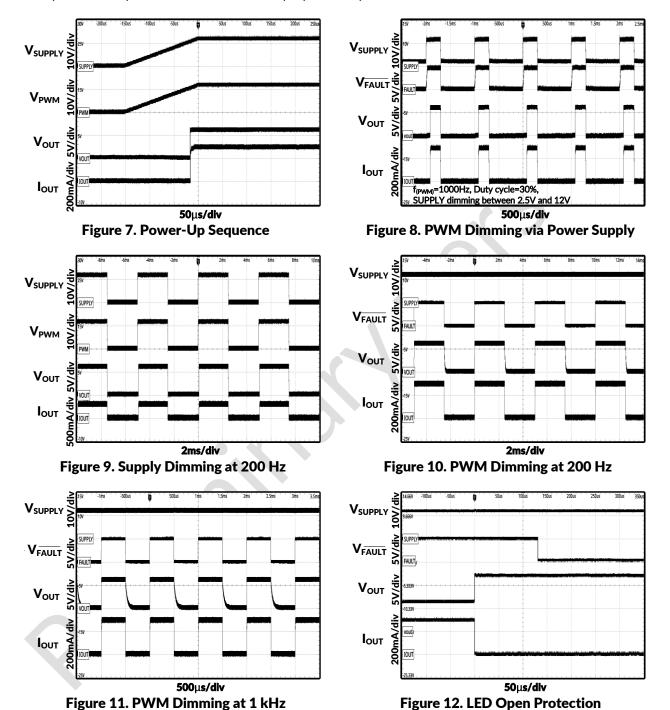


Figure 6. PWM Output Duty Cycle vs Input Duty Cycle



Typical Characteristics (continued)

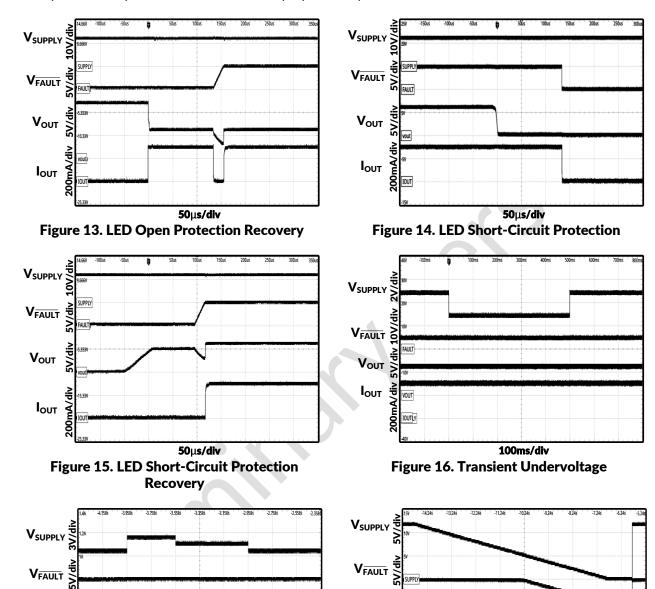
NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.





Typical Characteristics (continued)

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.



 \textbf{V}_{OUT}

lout

Figure 17. Transient Overvoltage

200ms/div

Vout

lout

Figure 18. Slow Decrease and Quick Increase of Supply Voltage

1s/div



Typical Characteristics (continued)

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

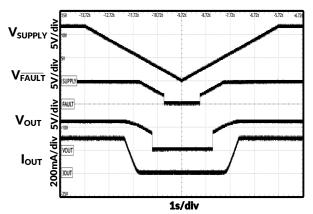


Figure 19. Slow Decrease and Slow Increase of Supply Voltage

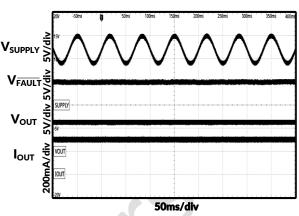


Figure 20. Superimposed Alternating Voltage 15Hz

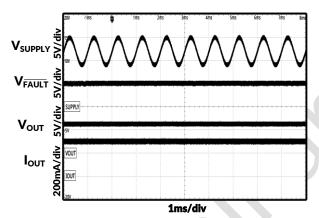


Figure 21. Superimposed Alternating Voltage 1kHz

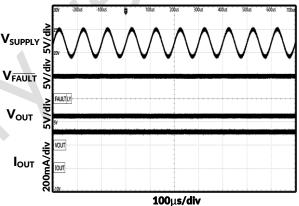


Figure 22. Superimposed Alternating Voltage 10kHz

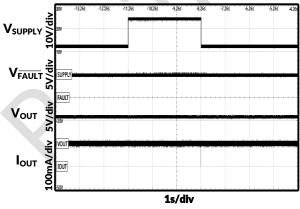


Figure 23. Jump Start



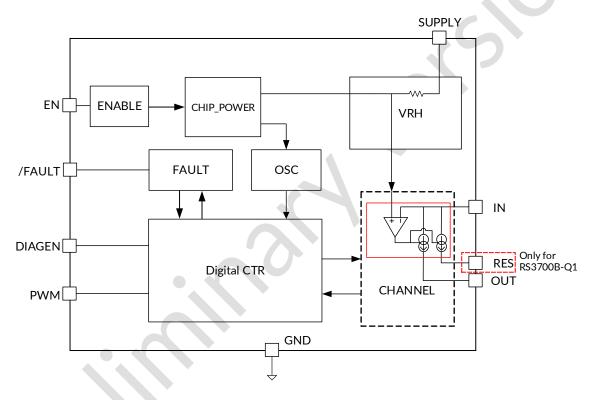
8 DETAILED DESCRIPTION

8.1 Overview

The RS3700-Q1 device is one of a family of single-channel linear LED drivers. The family provides a simple solution for automotive LED applications. Different package options in the family provide a variety of current ranges and diagnostic options. The RS3700-Q1 device in an EMSOP8 package supports LED open-circuit detection and short-to-ground detection. A one-fails-all-fail fault bus allows the RS3700-Q1 device to be used together with other LED drivers.

The output current can be set by an external $R_{(SNS)}$ resistor. Current flows from the supply through the $R_{(SNS)}$ resistor into the internal current source and to the LEDs.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Device Bias

8.3.1.1 Power-On Reset (POR)

The RS3700-Q1 device has an internal power-on-reset (POR) function. When power is applied to SUPPLY, the internal POR holds the device in the reset condition until $V_{(SUPPLY)}$ reaches $V_{(POR_rising)}$.

8.3.1.2 Low-Quiescent-Current Fault Mode

The RS3700-Q1 device consumes minimal quiescent current when it is in fault mode. If the \overline{FAULT} voltage is externally pulled LOW, the device shuts down the output driver.

If the device detects an internal fault, it pulls the \overline{FAULT} output LOW to signal a fault alarm on the one-fails-all-fail fault bus.

8.3.2 Constant-Current Driver

The RS3700-Q1 device has a high-side constant-current integrated driver. The device senses channel current with an external high-side current-sense resistor, R_(SNS). A current regulation loop drives an internal transistor



and regulates the current-sense voltage at the current-sense resistor to $V_{(CS_REG)}$. When the output driver is in regulation, the output current can be set using the following equation.

$$I_{(OUT)} = \frac{V_{(CS_REG)}}{R_{(SNS)}} \tag{1}$$

8.3.3. Output Current Thermal Balancing (RS3700B-Q1 only)

The RS3700B-Q1 device provides two current output path. Current flows through the R_{SNS} into the integrated current regulation circuit and to the LEDs through OUT pin and RES pin. The current output on both OUT pin and RES pin is independently regulated to achieve total required current output. The summed current of OUT and RES is equal to the current through the R_{SNS} .

$$I_{Total} = \frac{V_{(CS_REG)}}{R_{(SNS)}} = I_{OUT} + I_{RES}$$
 (2)

The integrated independent current regulation in RS3700B-Q1 dynamically adjusts the output current on both OUT and RES output to maintain the stable summed current for LED. The RS3700B-Q1 always regulates the current output to the RES pin as much as possible until the RES current path is saturated, and the rest of required current is regulated from the OUT. As a result, the most of the current to LED outputs through the RES pin when the voltage dropout is relatively high between SUPPLY and LED required total forward voltage. In the opposite case, the most of the current to LED outputs through the OUT pin when the voltage headroom is relatively low between SUPPLY and LED required forward voltage.

8.3.4 Device Enable

The RS3700-Q1 device has an enable input EN. When EN is low, the device is in sleep mode with ultralow quiescent current I(Shutdown). This low current helps to save system-level current consumption in applications where battery voltage directly connects to the device without high-side switches.

8.3.5 PWM Dimming

The RS3700-Q1 device supports PWM dimming via PWM input dimming and supply dimming.

The PWM input functions as an enable for the output current. When the PWM input is low, the device also disables the diagnostic features.

Supply dimming applies PWM dimming on the power input. For an accurate PWM threshold, RUNIC recommends using a resistor divider on the PWM input stage to set the PWM threshold higher than V_(POR_rising).

8.3.5.1 Power Supply Control

The RS3700-Q1 can support supply control to turn ON and OFF output current. When the voltage applied on the SUPPLY pin is higher than the LED string forward voltage plus needed headroom voltage ($V_{DROPOUT} + V_{CS_REG}$), and the PWM pin voltage is high, the output current is turned ON and well regulated. When the voltage applied on the SUPPLY pin drops below UVLO, the output current is turned OFF. With this feature, the power supply voltage in designed pattern can control the output current ON/OFF. The brightness is adjustable if the ON/OFF frequency is fast enough.



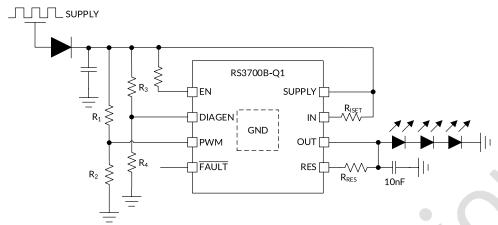


Figure 24. RS3700B-Q1 Power Supply Control LED Brightness Dimming

To avoid the output current overshoot during turn-on phase, it is suggested to enable the PWM through resistor as below connection:

$$V_{SUPPLY_PWM_rising} = V_{IH_PWM} \times \left(1 + \frac{R_1}{R_2}\right)$$
 (3)

$$V_{SUPPLY_PWM_rising} \ge V_{LED_FWD_TOT} + V_{DROPOUT} + V_{CS_REG}$$
 (4)

To avoid the false open-load detection due to low-dropout region operation during turn-off phase, it is suggested to enable the DIAGEN through resistor as below connection:

$$V_{SUPPLY_DIAGEN_falling} = V_{IL_DIAGEN_} \times \left(1 + \frac{R_3}{R_4}\right) \tag{5}$$

$$V_{SUPPLY_DIAGEN_falling} \geq V_{LED_FWD_TOT} + V_{OPEN_th_falling} + V_{CS_REG} \tag{6}$$

VSUPPLY DIAGEN falling
$$\geq$$
 VLED FWD TOT + VOPEN th falling + VCS REG (6)

8.3.6 Diagnostics

The RS3700-Q1 device provides advanced diagnostics and fault protection features for automotive exterior lighting systems. The device is able to detect and protect from LED string short-to-GND and LED string opencircuit faults. It also supports a one-fails-all-fail fault bus that could flexibly fit different regulatory requirements.

8.3.6.1 **DIAGEN**

The RS3700-Q1 device supports the DIAGEN pin with an accurate threshold to disable the open-load diagnostic function. With a resistor divider, the DIAGEN pin can be used to sense SUPPLY voltage with a resistorprogrammable threshold. With the DIAGEN feature, the device is able to avoid false error reports due to low dropout voltage and to drive maximum current in low-dropout mode when the input voltage is not high enough for current regulation.

When $V_{(DIAGEN)}$ is higher than the $V_{IH(DIAGEN)}$ threshold, the device enables the LED open-circuit diagnostic. When $V_{(DIAGEN)}$ is lower than the $V_{IL(DIAGEN)}$ threshold, the device disables the LED open-circuit diagnostic.

8.3.6.2 Low-Dropout Mode

When the supply voltage drops, the RS3700-Q1 device tries to regulate current by driving internal transistors in the linear region, also known as low-dropout mode, because the voltage across the sense resistor fails to reach the regulation target.

In low-dropout mode, the open-circuit diagnostic must be disabled. Otherwise, the device treats the low-dropout mode as an open-circuit fault. The DIAGEN pin is used to avoid false diagnostics on the output channel due to low supply voltage.



When the DIAGEN voltage is low, open-circuit detection is ignored. When the DIAGEN voltage is high, open-circuit detection returns to normal operation.

In low-dropout mode, a parallel diode and current-limiting resistor are recommended to clamp between SUPPLY and IN (across the sense resistor) in case of a large current pulse during recovery.

8.3.6.3 Open-Circuit Detection

The RS3700-Q1 device has LED open-circuit detection. Open-circuit detection monitors the output voltage when the channel is in the ON state. Open-circuit detection is only enabled when DIAGEN is HIGH. A short-to-battery fault is also detected as an LED open-circuit fault.

The device monitors dropout-voltage differences between the IN and OUT pins when PWM is HIGH. The voltage difference $V_{(IN)} - V_{(OUT)}$ is compared with the internal reference voltage $V_{(OPEN_th_rising)}$ to detect an LED open-circuit failure. If $V_{(IN)} - V_{(OUT)}$ falls below the $V_{(OPEN_th_rising)}$ voltage longer than the deglitch time of $t_{(OPEN_deg)}$, the device detects an open-circuit fault. Once an LED open-circuit failure is detected, the constant-current source pulls the fault bus down. During the deglitch time period, if $V_{(IN)} - V_{(OUT)}$ rises above $V_{(OPEN_th_falling)}$, the deglitch timer is reset.

When the PWM input is in auto-retry, the device keeps the output ON to retry if the PWM input is HIGH; the device sources a small current I_(retry) from IN to OUT to retry when the PWM input is LOW. In either scenario, once a faulty channel recovers, the device resumes normal operation and releases the FAULT pulldown.

8.3.6.4 Short-to-GND Detection

The RS3700-Q1 device has LED short-to-GND detection. Short-to-GND detection monitors the output voltage when the channel is in the ON state. Once a short-to-GND LED failure is detected, the device turns off the output channel and retries automatically, ignoring the PWM input. If the retry mechanism detects removal of the LED short-to-GND fault, the device resumes normal operation.

The device monitors the $V_{(OUT)}$ voltage and compares it with the internal reference voltage to detect a short-to-GND failure. If $V_{(OUT)}$ falls below $V_{(SG_th_rising)}$ longer than the deglitch time of $t_{(SG_deg)}$, the device asserts the short-to-GND fault and pulls \overline{FAULT} low. During the deglitching time period, if $V_{(OUT)}$ rises above $V_{(SG_th_falling)}$, the timer is reset.

Once the device has detected a short-to-GND fault, the device turns off the output channel and retries automatically with a small current. When retrying, the device sources a small current $I_{(retry)}$ from IN to OUT to pull up the LED loads continuously. Once auto-retry detects output voltage rising above $V_{(SG_th_falling)}$, it clears the short-to-GND fault and resumes normal operation.

8.3.6.5 Overtemperature Protection

The RS3700-Q1 device monitors device junction temperature. When the junction temperature reaches thermal shutdown threshold $T_{(TSD)}$, the output shuts down. Once junction temperature falls below $T_{(TSD)} - T_{(TSD_HYS)}$, the device resumes normal operation. During overtemperature protection, the fault bus is pulled low.

8.3.7 Fault-Bus Output With One-Fails-All-Fail

The RS3700-Q1 device has a fault bus for diagnostics output. In normal operation, \overline{FAULT} is weakly pulled up by an internal pullup current source $I_{(FAULT_pullup)}$ higher than $V_{OH(FAULT)}$. If any fault occurs, the fault bus is strongly pulled low by the internal pulldown current source $I_{(FAULT_pulldown)}$. Once $V_{(\overline{FAULT})}$ falls below $V_{IL(FAULT)}$, all outputs shut down for protection. The faulty channel keeps retrying until the fault is removed.

If FAULT is externally pulled up with a current larger than I_(FAULT_pulldown), the one-fails-all-fail function is disabled and only the faulty channel is turned off.

The fault bus is able to support up to 15 pieces of LED devices.



	Table 1.1 date table With Dix GET THOST								
FAULT BUS STATUS	FAULT TYPE	DETECTION MECHANISM	CHANNEL STATE	DEGLITCH TIME	FAULT BUS	FAULT HANDLING ROUTINE	FAULT RECOVERY		
FAULT floating or externally pulled up	Open-circuit or short-to- supply	V(IN) - V(OUT) < V(OPEN_th_rising)	On	t(OPEN_deg)	Constant- current pulldown	Device works normally with FAULT pin pulled low. Device sources l _(retry) current when PWM is LOW. Device keeps output normal when PWM is HIGH.	Auto recover		
	Short-to- ground	$V_{(OUT)} < V_{(SG_th_rising)}$	On	t(sg_deg)	Constant- current pulldown	Device turns output off and retries with constant current I _(retry) , ignoring the PWM input.	Auto recover		
	Over- temperature	$T_J > T_{(TSD)}$	On or off	t _(TSD_deg)	Constant- current pulldown	Device turns output off.	Auto recover		
Externally pulled low			D	evice turns o	output off				

Table 2. Fault Table With DIAGEN = LOW

	I GASIO EL I GGIO IVIGII DINCEIT EGIT								
FAULT BUS STATUS	FAULT TYPE	DETECTION MECHANISM	CHANNEL STATE	DEGLITCH TIME	FAULT BUS	FAULT HANDLING ROUTINE	FAULT RECOVERY		
	Open-circuit or short-to- supply				Ignored				
FAULT floating or externally pulled up	Short-to- ground	V _(OUT) < V(SG_th_rising)	On	t(SG_deg)	Constant- current pulldown	Device turns output off and retries with constant current I _(retry) , ignoring the PWM input.	Auto recover		
	Over- temperature	T」> T _(TSD)	On or off	t(TSD_deg)	Constant- current pulldown	Device turns output off.	Auto recover		
Externally pulled low		Device turns output off.							

8.4 Device Functional Modes

8.4.1 Undervoltage Lockout, V(SUPPLY) < V(POR_rising)

When the device is in undervoltage lockout mode, the RS3700-Q1 device disables all functions until the supply rises above the POR-rising threshold.

8.4.2 Normal Operation V_(SUPPLY) ≥ 4.5 V

The device drives an LED string in normal operation. With enough voltage drop across SUPPLY and OUT, the device is able to drive the output in constant-current mode.

8.4.3 Low-Voltage Dropout

When the device drives an LED string in low-dropout mode, if the voltage drop is less than the open-circuit detection threshold, the device may report a false open. Set the DIAGEN threshold higher than the LED string voltage to avoid a false open-circuit detection.

8.4.4 Fault Mode

When the device detects an open or shorted LED, the device tries to pull down the FAULT pin with a constant current. If the fault bus is pulled down, the device switches to fault mode and consumes a fault current of I(FAULT).



9 POWER SUPPLY RECOMMENDATIONS

The RS3700-Q1 device is qualified for automotive applications. The normal power supply connection is therefore to an automobile electrical system that provides a voltage within the range specified in the Recommended Operating Conditions.

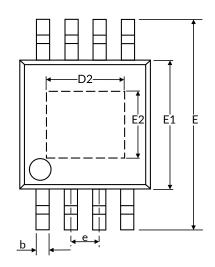
10 LAYOUT

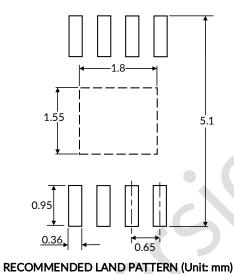
10.1 Layout Guideline

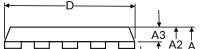
Thermal dissipation is the primary consideration for RS3700-Q1 layout. RUNIC recommends good thermal dissipation area connected to thermal pads with thermal vias.



11 PACKAGE OUTLINE DIMENSIONS EMSOP8 (4)









			' '				
Completed	Dimensions I	n Millimeters	Dimensions In Inches				
Symbol	Min	Max	Min	Мах			
A (1)	-	1.100	-	0.043			
A1	0.050	0.150	0.002	0.006			
A2	0.750	0.950	0.030	0.037			
A3	0.300	0.400	0.012	0.016			
b	0.280	0.360	0.011	0.014			
С	0.150	0.190	0.006	0.007			
D (1)	2.900	3.100	0.114	0.122			
D2	1.800	REF (2)	0.071 REF ⁽²⁾				
E	4.700	5.100	0.185	0.201			
E1 (1)	2.900	3.100	0.114	0.122			
E2	1.550	REF (2)	0.061 REF ⁽²⁾				
е	0.650 [BSC (3)	0.026	BSC (3)			
L	0.400	0.400 0.700		0.028			
L1	0.950	REF (2)	0.037 REF ⁽²⁾				
θ	0°	8°	0°	8°			

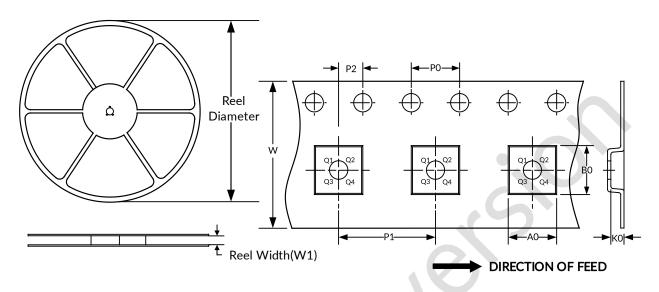
NOTE:

- 1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
- 2. REF is the abbreviation for Reference.
- 3. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
- 4. This drawing is subject to change without notice.



12 TAPE AND REEL INFORMATION REEL DIMENSIONS

TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width(mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
EMSOP8	13"	12.4	5.20	3.30	1.50	4.0	8.0	2.0	12.0	Q1

NOTE:

- 1. All dimensions are nominal.
- 2. Plastic or metal protrusions of 0.15mm maximum per side are not included.



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